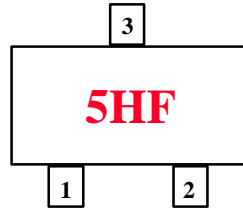
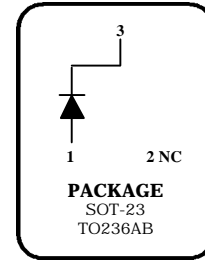


MMBD701

PACKAGE
SOT-23
TO-236AB (Low)



CONNECTION DIAGRAM



Schottky Barrier Diode

Sourced from Process GE

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

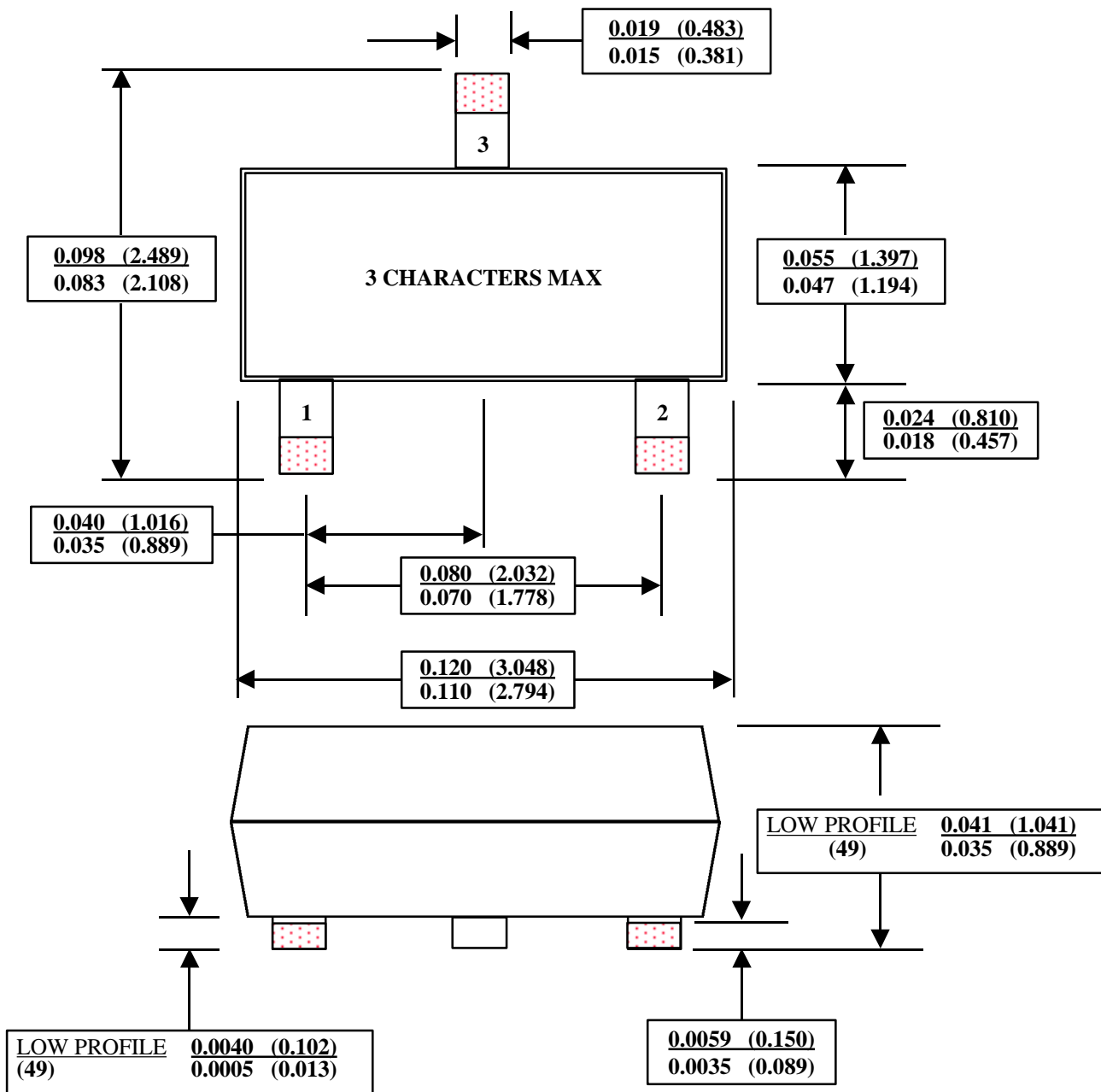
Sym	Parameter	Value	Units
T_{stg}	Storage Temperature	-55 to +150	°C
T_J	Operating Junction Temperature	-55 to +125	°C
W_{IV}	Working Inverse Voltage	35	V
P_F	Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	200 2.0	mW Mw/°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

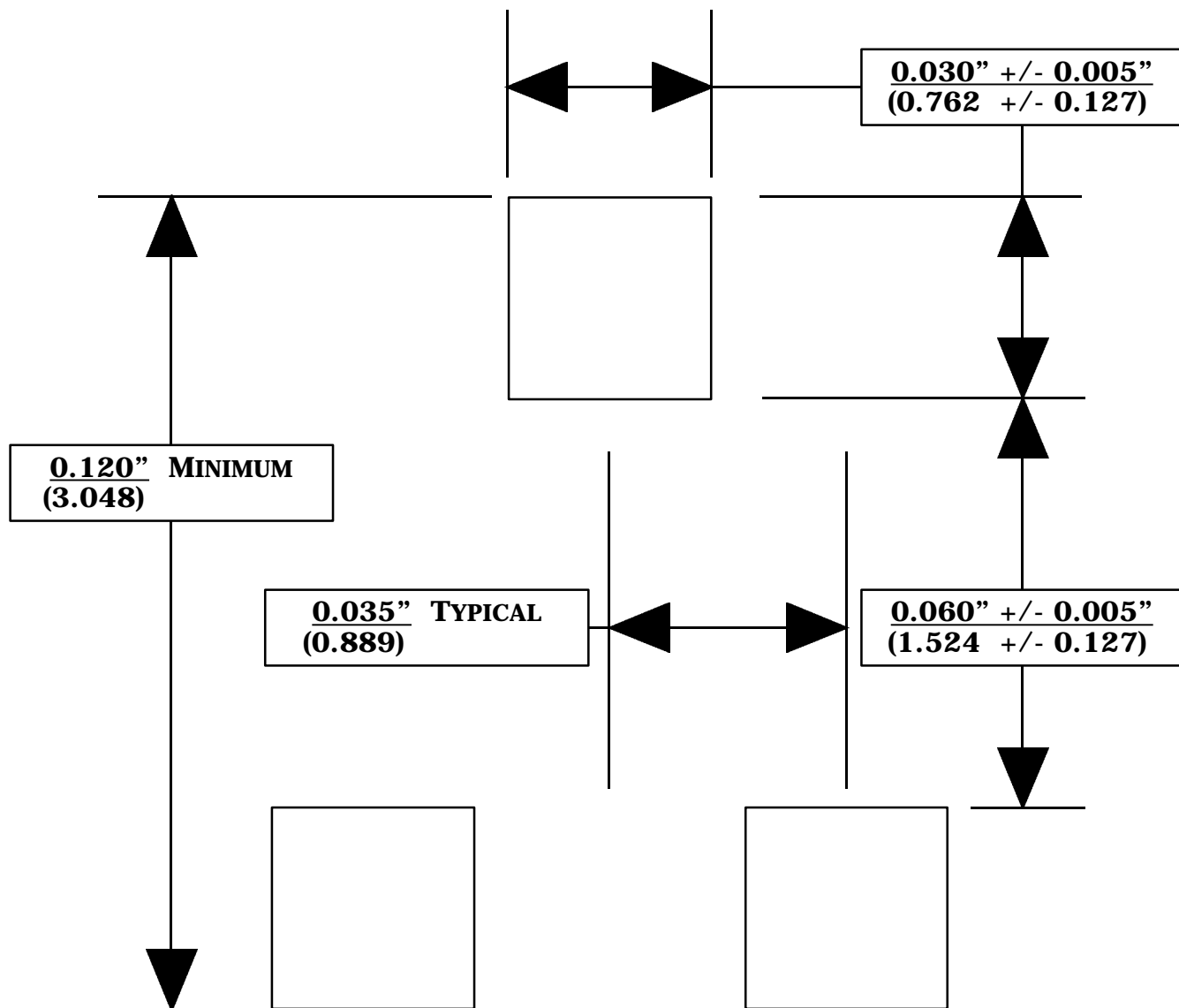
ADVANCED INFORMATION ONLY NOT IN PRODUCTION

Electrical Characteristics TA = 25°C unless otherwise noted

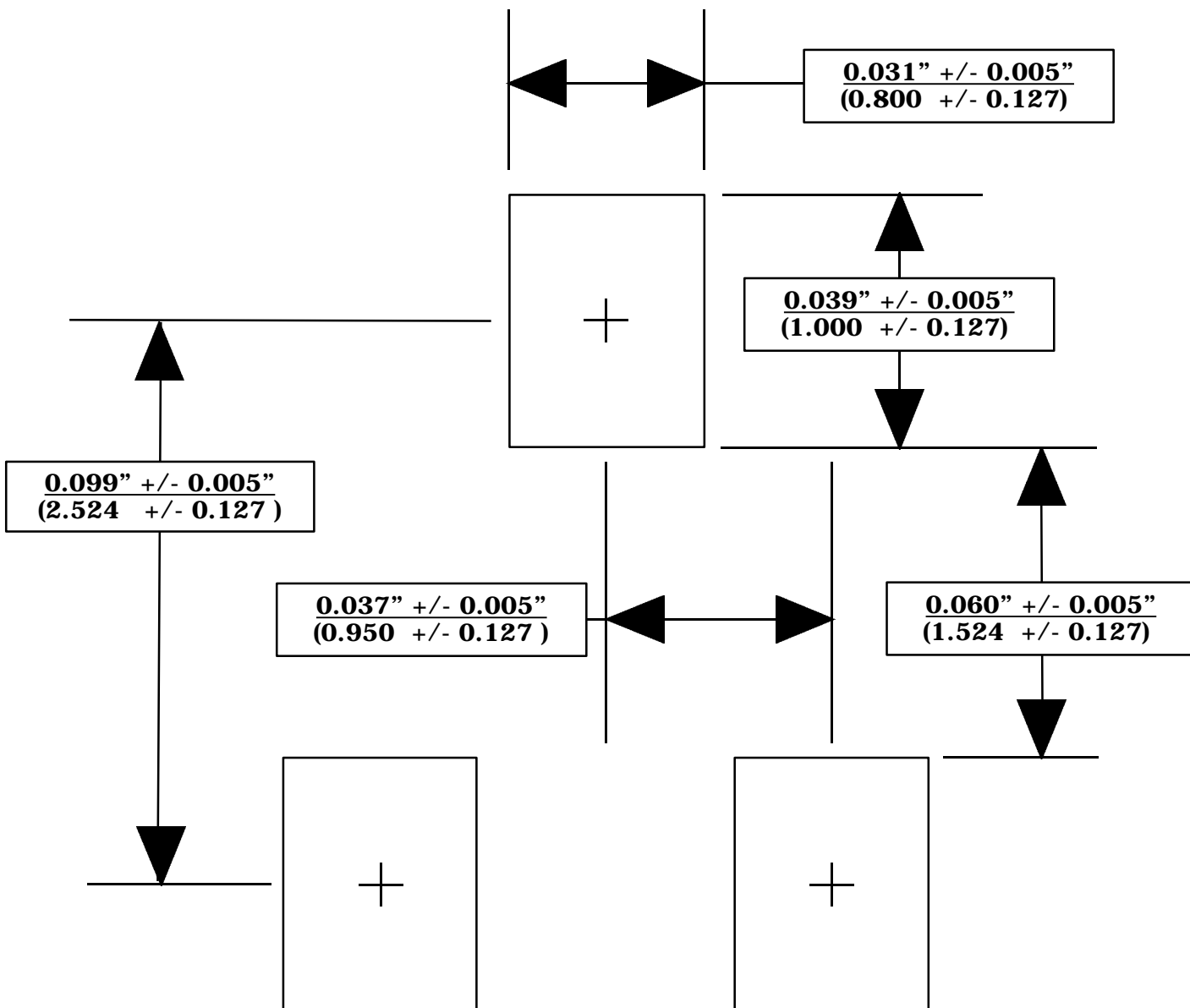
SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B_V	Breakdown Voltage	70		V	$I_R = 10 \mu\text{A}$
I_R	Reverse Leakage		200	nA	$V_R = 35 \text{ V}$
V_F	Forward Voltage		500 1.0	mV V	$I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$
C_T	Capacitance		1.0	pF	$V_R = 20 \text{ V}$ $f = 1.0 \text{ MHz}$



SOT-23
TO-236AB (LOW PROFILE)
22-August-1994



**RECOMMENDED SOLDER PADS
FOR
SOT-23**



**RECOMMENDED SOLDER PADS
FOR
U.S. & European SOT-23
&
Japanese SC-59**

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E ² CMOS TM	LittleFET TM	Quiet Series TM	VCX TM
EnSigna TM	MicroFET TM	SILENT SWITCHER [®]	
FACT TM	MICROWIRE TM	SMART START TM	
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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